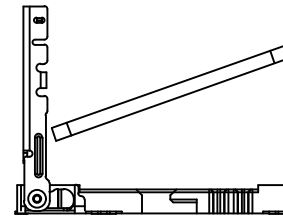
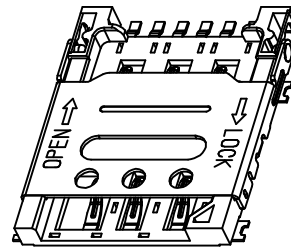
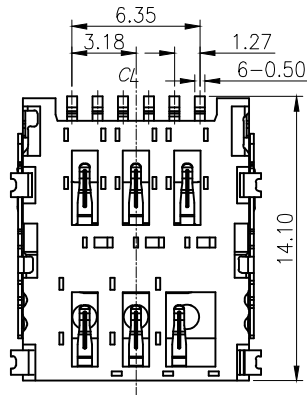
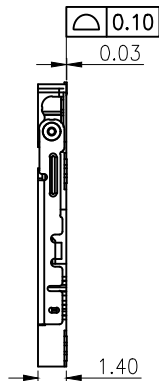
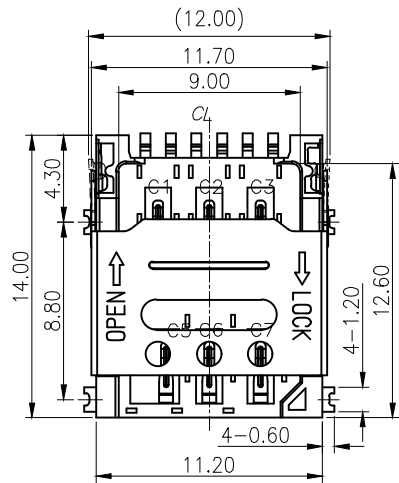


RoHS



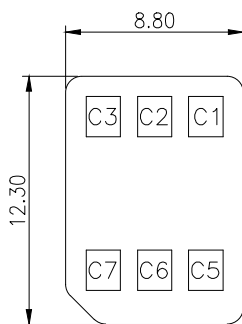
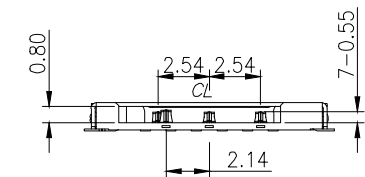
STEP 1 INSERT NANO SIM CARD



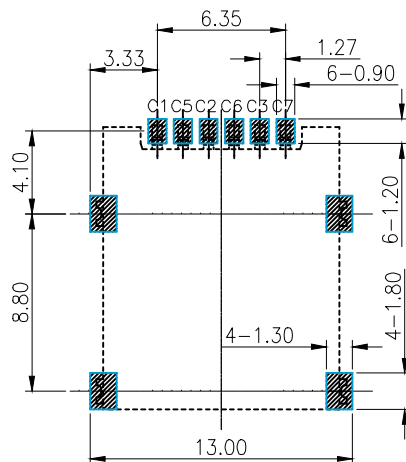
STEP 2 PUSH THE SHELL



STEP 3 FINISH



PIN NO.	PIN NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED PCB LAYOUT
TOLERANCE ±0.05

■ SMT SOLDER AREA

NOTES:

1. MATERIAL:

- 1.1 Housing: High Temperature Thermoplastic UL94V-0; Color Black.
- 1.2 Terminal: Copper Alloy, T=0.12mm.
- 1.3 Shell: Stainless Steel, T=0.20mm.

2. FINISH:

- 2.1 Terminal: Plated Gold on the Contact Area and Solder Tails
- 2.2 Peg: Plated Gold on the Solder Tails.

3. SPECIALITY:

- 3.1 Rated current: 0.5A
- 3.2 Rated voltage: 50V
- 3.3 Contact Resistance: 80mΩ MAX
- 3.4 Insulation Resistance: 100MΩ MIN 100V DC
- 3.5 Dielectric withstanding voltage: 100V AC.
- 3.6 Solder ability: 245±5°C, 5±0.5s.
- 3.7 Operating condition: Temperature: -30°C~+80°C Humidity: 80% R.H MAX

E		PRODUCT SPEC. NANO SIM	
TITLE:		NANO SIM 6PIN 高度1.4H	
PART NO.		XXX-0029-06140(A)	
FILE NAME.			
SCALE	1:1	UNIT:mm	A4 SHEET: 1 of 1

General	Angle	设计	赵文博	16'/12/22
X±0.50	X'±2°	设计	赵文博	16'/12/22
.X±0.30	.X'±1°	校阅	赵文博	16'/12/22
.XX±0.20	.XX'±0.5°	承认	张九航	16'/12/22
GENERAL TOLERANCE UNLESS OTHERWISE NOTED		承认	张九航	16'/12/22

工程变更通知单号	版次	日期	新发行	赵文博
ECN(DCN) NO.	REV	DATE	DESCRIPTION	CHANGE APPRO.